

# MMBZxxVAWT1G Series, SZMMBZxxVAWT1G Series

## 40 Watt Peak Power Zener Transient Voltage Suppressors

### SC-70 Dual Common Anode Zeners for ESD Protection

These dual monolithic silicon Zener diodes are designed for applications requiring transient overvoltage protection capability. They are intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment and other applications. Their dual junction common anode design protects two separate lines using only one package. These devices are ideal for situations where board space is at a premium.

#### Features

- SC-70 Package Allows Either Two Separate Unidirectional Configurations or a Single Bidirectional Configuration
- Working Peak Reverse Voltage Range
- Standard Zener Breakdown Voltage Range: 15 – 33 V
- Peak Power – 40 W @ 1.0 ms (Unidirectional), per Figure 5 Waveform
- ESD Rating:
  - Class 3B (> 16 kV) per the Human Body Model
  - Class C (> 400 V) per the Machine Model
- Low Leakage < 5.0  $\mu$ A
- Flammability Rating UL 94 V-0
- AEC-Q101 Qualified and PPAP Capable – SZMMBZxxVAWT1G
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These are Pb-Free Devices\*

#### Mechanical Characteristics:

**CASE:** Void-free, transfer-molded, thermosetting plastic case

**FINISH:** Corrosion resistant finish, easily solderable

#### MAXIMUM CASE TEMPERATURE FOR SOLDERING PURPOSES:

260°C for 10 Seconds

Package designed for optimal automated board assembly

Small package size for high density applications

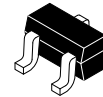
Available in 8 mm Tape and Reel

Use the Device Number to order the 7 inch/3,000 unit reel.

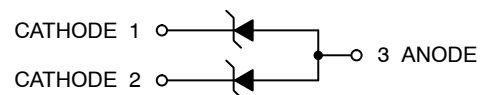


ON Semiconductor®

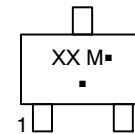
<http://onsemi.com>



SC-70  
CASE 419  
STYLE 4



#### MARKING DIAGRAM



XX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MMBZxxVAWT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel
SZMMBZxxVAWT1G	SC-70 (Pb-Free)	3,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### DEVICE MARKING INFORMATION

See specific marking information in the device marking column of the table on page 2 of this data sheet.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MMBZxxVAWT1G Series, SZMMBZxxVAWT1G Series

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Power Dissipation @ 1.0 ms (Note 1) @ $T_L \leq 25^\circ\text{C}$	$P_{pk}$	40	W
Total Power Dissipation on FR-5 Board (Note 2) @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	200 1.6	mW mW/ $^\circ\text{C}$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	618	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{stg}$	- 55 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

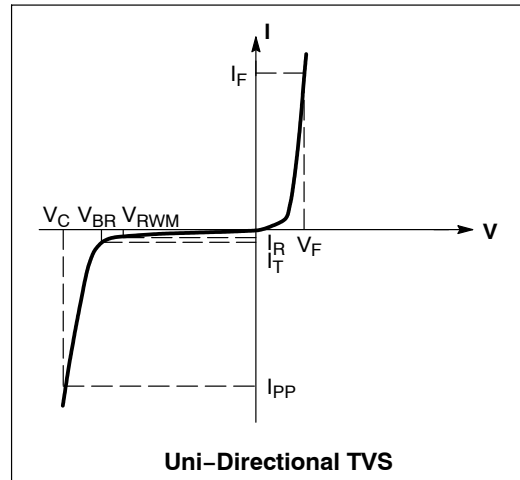
1. Non-repetitive current pulse per Figure 5 and derate above  $T_A = 25^\circ\text{C}$  per Figure 6.
2. FR-5 = 1.0 x 0.75 x 0.62 in.

## ELECTRICAL CHARACTERISTICS

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

**UNIDIRECTIONAL** (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$V_{RWM}$	Working Peak Reverse Voltage
$I_R$	Maximum Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$\Theta V_{BR}$	Maximum Temperature Coefficient of $V_{BR}$
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$
$Z_{ZT}$	Maximum Zener Impedance @ $I_{ZT}$
$I_{ZK}$	Reverse Current
$Z_{ZK}$	Maximum Zener Impedance @ $I_{ZK}$



**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

**UNIDIRECTIONAL** (Circuit tied to Pins 1 and 3 or Pins 2 and 3)

( $V_F = 0.9\text{ V Max @ } I_F = 10\text{ mA}$ )

Device*	Device Marking	$V_{RWM}$ Volts	$I_R$ @ $V_{RWM}$ nA	Breakdown Voltage			$V_C$ @ $I_{PP}$ (Note 4)		$\Theta V_{BR}$ mV/ $^\circ\text{C}$	
				$V_{BR}$ (Note 3) (V)			$V_C$	$I_{PP}$		
				Min	Nom	Max				@ $I_T$ mA
MMBZ15VAWT1G	AT	12	50	14.25	15	15.75	1.0	21	1.9	12.3
MMBZ20VAWT1G	AU	17	50	19.00	20	21.00	1.0	28	1.4	17.2
MMBZ27VAWT1G	AA	22	50	25.65	27	28.35	1.0	40	1.0	24.3
MMBZ33VAWT1G	AV	26	50	31.35	33	34.65	1.0	46	0.87	30.4

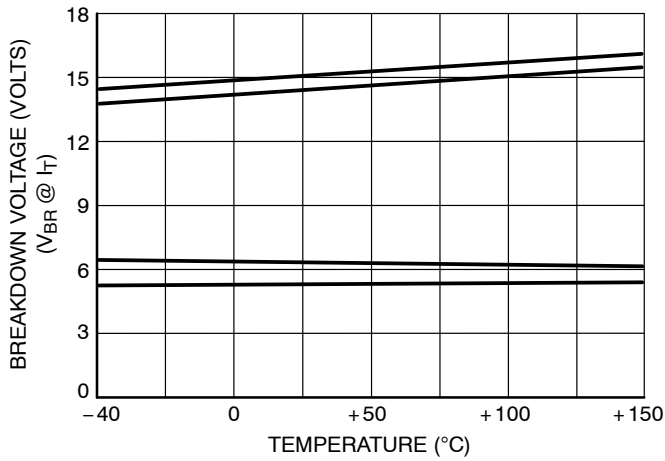
3.  $V_{BR}$  measured at pulse test current  $I_T$  at an ambient temperature of  $25^\circ\text{C}$ .

4. Surge current waveform per Figure 5 and derate per Figure 6

\*Include SZ-prefix devices where applicable.

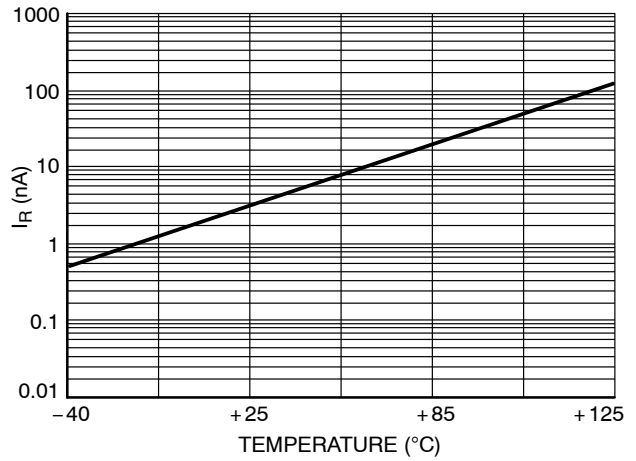
# MMBZxxVAWT1G Series, SZMMBZxxVAWT1G Series

## TYPICAL CHARACTERISTICS

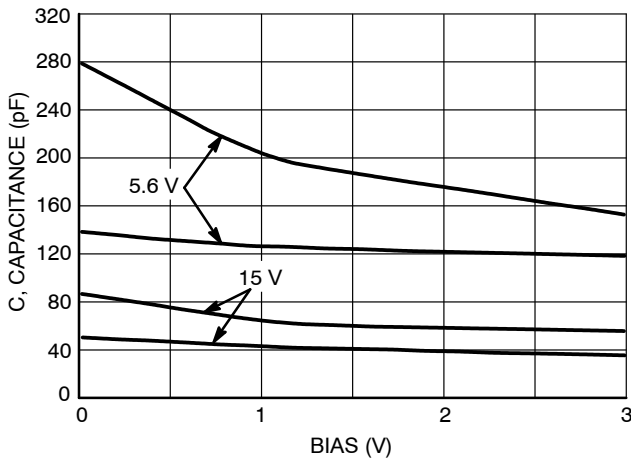


**Figure 1. Typical Breakdown Voltage versus Temperature**

(Upper curve for each voltage is bidirectional mode, lower curve is unidirectional mode)

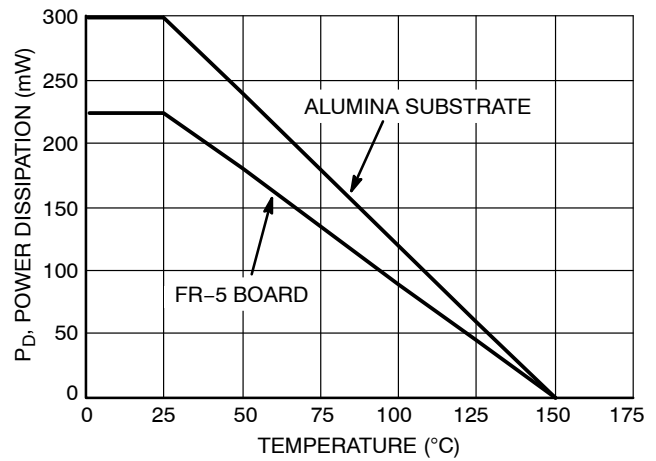


**Figure 2. Typical Leakage Current versus Temperature**



**Figure 3. Typical Capacitance versus Bias Voltage**

(Upper curve for each voltage is unidirectional mode, lower curve is bidirectional mode)



**Figure 4. Steady State Power Derating Curve**

TYPICAL CHARACTERISTICS

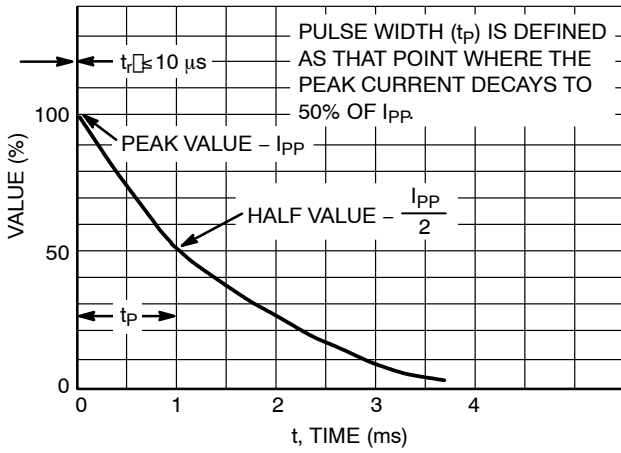


Figure 5. Pulse Waveform

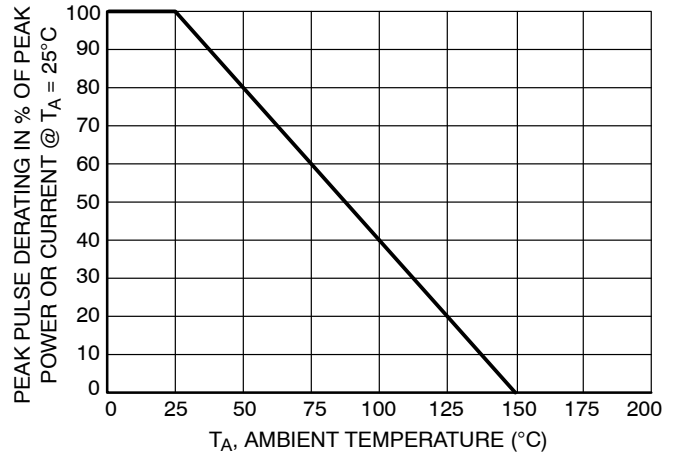


Figure 6. Pulse Derating Curve

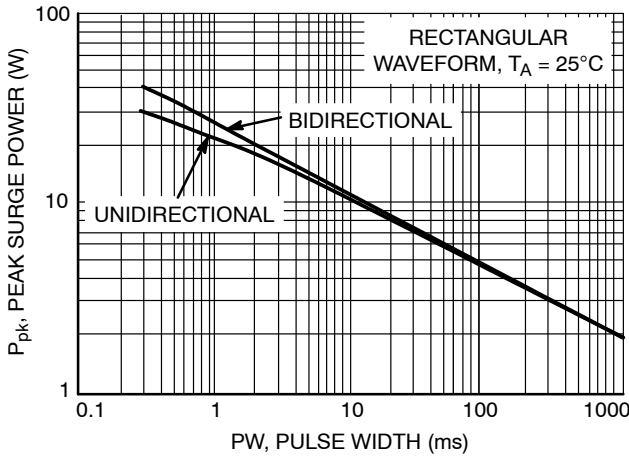


Figure 7. Maximum Non-repetitive Surge Power,  $P_{pk}$  versus PW

Power is defined as  $V_{RSM} \times I_Z(pk)$  where  $V_{RSM}$  is the clamping voltage at  $I_Z(pk)$ .

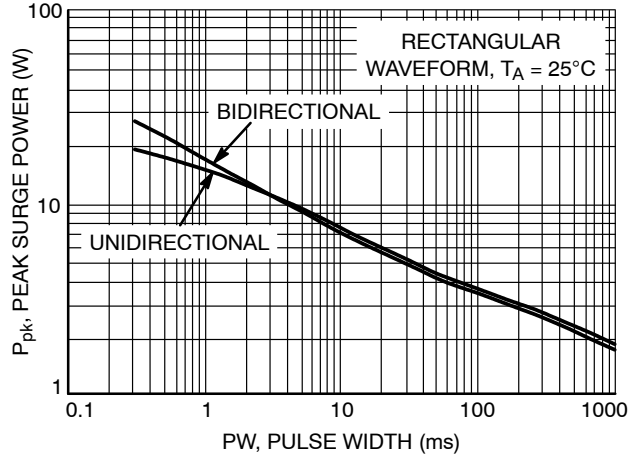


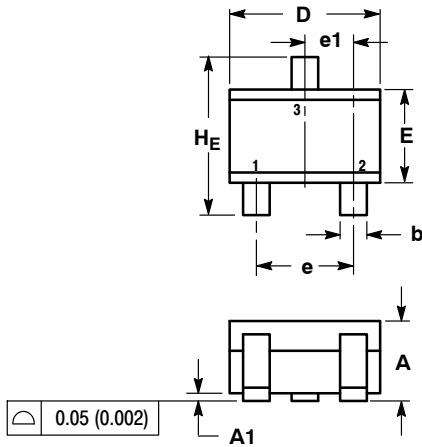
Figure 8. Maximum Non-repetitive Surge Power,  $P_{pk}(NOM)$  versus PW

Power is defined as  $V_Z(NOM) \times I_Z(pk)$  where  $V_Z(NOM)$  is the nominal Zener voltage measured at the low test current used for voltage classification.

# MMBZxxVAWT1G Series, SZMMBZxxVAWT1G Series

## PACKAGE DIMENSIONS

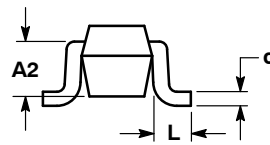
SC-70 (SOT-323)  
CASE 419-04  
ISSUE N



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

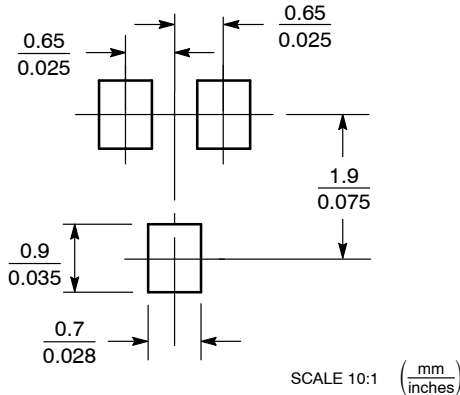
DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.70 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.20	0.38	0.56	0.008	0.015	0.022
HE	2.00	2.10	2.40	0.079	0.083	0.095



STYLE 4:

1. CATHODE
2. CATHODE
3. ANODE

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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